

8961726 TEXAS INSTR (OPT0)

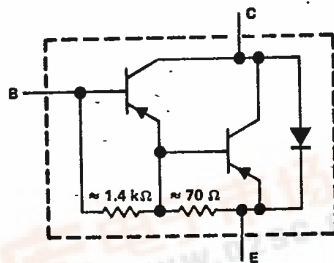
62C 36952 D

TIP605, TIP606, TIP607
P-N-P DARLINGTON-CONNECTED
SILICON POWER TRANSISTORS
 REVISED OCTOBER 1984

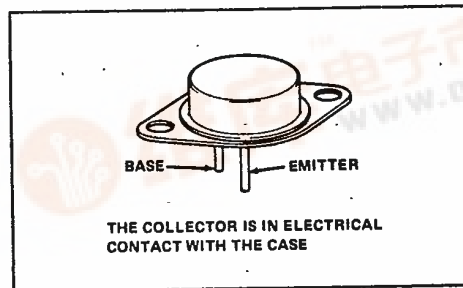
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- Designed For Complementary Use With TIP600, TIP601, TIP602
- 10 A Rated Collector Current
- Min h_{FE} of 200 at 4 V, 10 A
- Max I_{CEO} of 50 μ A
- Max $V_{CE(sat)}$ of 2.5 V at $I_C = 10$ A
- Similar to 2N6053, 2N6054, RCA8350, RCA8350A, RCA8350B

device schematic



TO-3 PACKAGE



absolute maximum ratings at 25°C case temperature (unless otherwise noted)

	TIP605	TIP606	TIP607
Collector-base voltage	-60 V	-80 V	-100 V
Collector-emitter voltage ($I_B = 0$)	-60 V	-80 V	-100 V
Emitter-base voltage	-5 V		
Continuous collector current	-10 A		
Peak collector current (see Note 1)	-15 A		
Continuous base current	-1 A		
Safe operating areas at (or below) 25°C case temperature	See Figures 7 and 8		
Continuous device dissipation at (or below) 25°C case temperature (see Note 2)	100 W		
Continuous device dissipation at (or below) 25°C free-air temperature (see Note 3)	5 W		
Operating collector junction and storage temperature range	-65°C to 200°C		
Lead temperature 3,2 mm (0.125 inch) from case for 10 seconds	300°C		

- NOTES:
1. This value applies for $t_W \leq 0.3$ ms, duty cycle $\leq 10\%$.
 2. Derate linearly to 200°C case temperature at the rate of 0.57 W/°C or refer to Dissipation Derating Curve, Figure 9.
 3. Derate linearly to 200°C free-air temperature at the rate of 26.6 mW/°C or refer to Dissipation Derating Curve, Figure 10.

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electrical characteristics at 25°C case temperature

PARAMETER	TEST CONDITIONS	TIP600			TIP601			TIP602			UNIT
		MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
V _{(BR)CEO}	I _C = -30 mA, I _B = 0, See Note 4	-60			-80			-100			V
I _{CEO}	V _{CE} = -30 V, I _B = 0			-50							μA
	V _{CE} = -40 V, I _B = 0						-50				
	V _{CE} = -50 V, I _B = 0								-50		
I _{CBO}	V _{CB} = -60 V, I _E = 0			-50							μA
	V _{CB} = -80 V, I _E = 0						-50				
	V _{CB} = -100 V, I _E = 0								-50		
I _{EBO}	V _{EB} = -5 V, I _C = 0			-8			-8			-8	mA
h _{FE}	V _{CE} = -4 V, I _C = -3 A, See Notes 4 and 5	1000	20000		1000	20000		1000	20000		
	V _{CE} = -4 V, I _C = -10 A, See Notes 4 and 5	200			200			200			
V _{BE}	V _{CE} = -4 V, I _C = -10 A, See Notes 4 and 5			-2.8			-2.8			-2.8	V
V _{CE(sat)}	I _B = -6 mA, I _C = -3 A, See Notes 4 and 5			-2			-2			-2	V
	I _B = -100 mA, I _C = -10 A, See Notes 4 and 5			-2.5			-2.5			-2.5	
V _F	I _F = 10 A, See Notes 4 and 5			3.5			3.5			3.5	V

NOTES: 4. These parameters must be measured using pulse techniques, t_w = 300 μs, duty cycle ≤ 2 %.
5. These parameters are measured with voltage-sensing contacts separate from the current-carrying contacts located within 3.2 mm (0.125 inch) from the device body.

thermal characteristics

PARAMETER	MIN	TYP	MAX	UNIT
R _{θJC}			1.75	°C/W
R _{θJA}			35	
R _{θCHS}	See Note 6		0.4	

NOTE 6: This parameter is measured using a 0.08 mm mica insulator with Dow-Corning 11 compound on both sides of the insulator, a 6-32 mounting screw with bushing, and a mounting torque of 0.9 mm Newton-meter.

resistive-load switching characteristic at 25°C case temperature

PARAMETER	TEST CONDITIONS†	MIN	TYP	MAX	UNIT
t _d	I _C = -8 A, I _{B1} = -80 mA, I _{B2} = 80 mA, V _{BE(off)} = 5 V, R _L = 5 Ω, See Figure 1		0.035		μs
t _r			0.3		
t _s			0.9		
t _f			1.3		

† Voltage and current values shown are nominal; exact values vary slightly with transistor parameters.

functional tests at 25°C free-air temperature

TEST	CONDITIONS	LEVEL
Power (V _{CE} * I _C)	V _{CE} = -40 V, I _C = -2 A, t _{test} = 0.15 s	80 W
Reverse Pulse Energy ($\frac{I_C^2 L}{2}$)	I _{CM} = -1 A, L = 20 mH, f = 10 Hz, t _{test} = 0.5 s, See Figure 2	10 mJ



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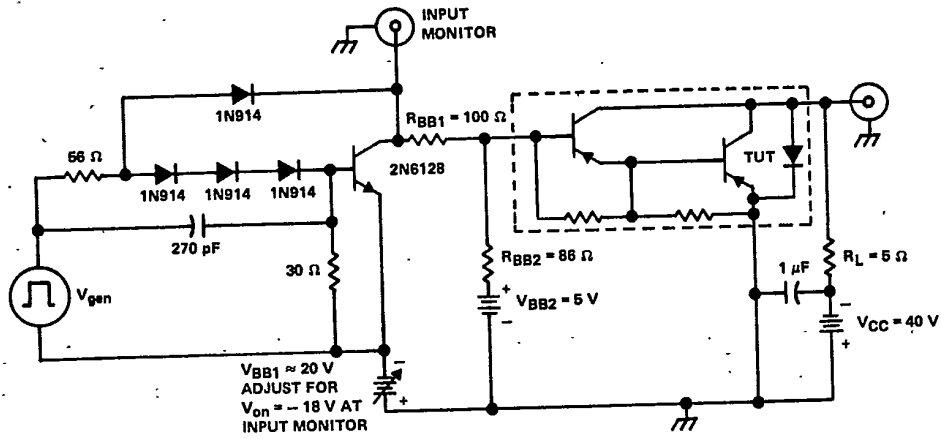
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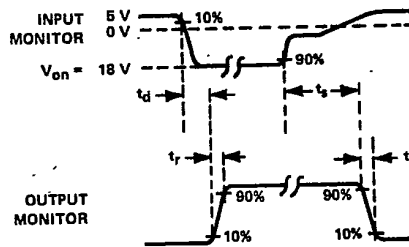
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PARAMETER MEASUREMENT INFORMATION

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TEST CIRCUIT



VOLTAGE WAVEFORMS

- NOTES:
- A. V_{gen} is a 30-V pulse into a 50 Ω termination.
 - B. The V_{gen} waveform is supplied by a generator with the following characteristics: $t_r < 15$ ns, $t_f < 15$ ns, $Z_{out} = 60 \Omega$, $t_w = 20 \mu s$, duty cycle = 2 %.
 - C. Waveforms are monitored on an oscilloscope with the following characteristics: $t_r < 15$ ns, $R_{in} > 10$ M Ω , $C_{in} < 11.5$ pF.
 - D. Resistors must be noninductive types.
 - E. The d-c power supplies may require additional bypassing in order to minimize ringing.

FIGURE 1. RESISTIVE-LOAD SWITCHING



TIP Devices

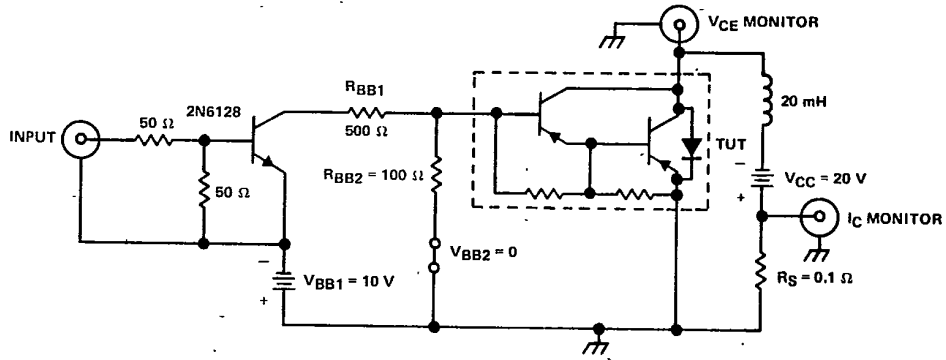
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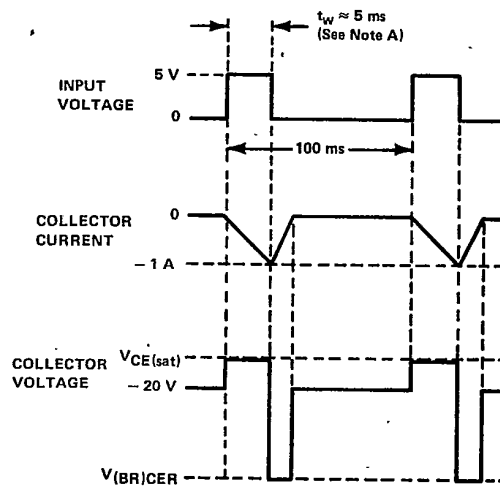
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PARAMETER MEASUREMENT INFORMATION



TEST CIRCUIT



VOLTAGE AND CURRENT WAVEFORMS

NOTE A: Input pulse duration is increased until $I_{CM} = 1$ A.

FIGURE 2. INDUCTIVE-LOAD SWITCHING

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TYPICAL CHARACTERISTICS

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STATIC FORWARD CURRENT TRANSFER RATIO
vs
COLLECTOR CURRENT

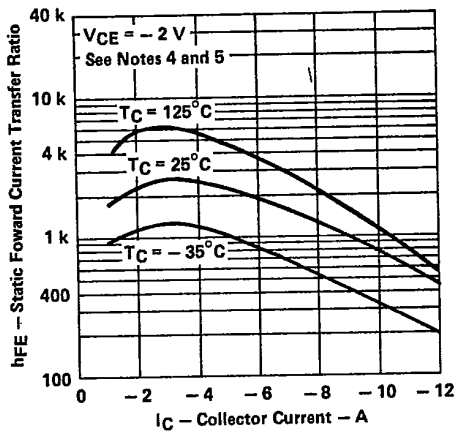


FIGURE 3

STATIC FORWARD CURRENT TRANSFER RATIO
vs
COLLECTOR CURRENT

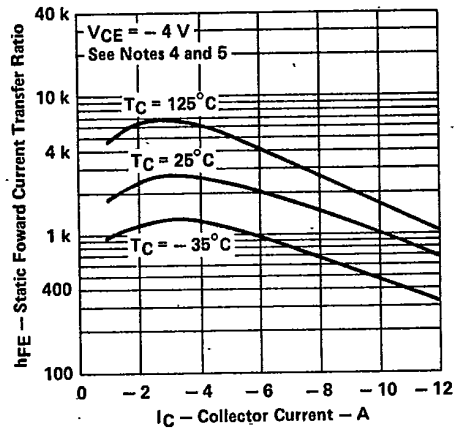


FIGURE 4

COLLECTOR-EMITTER SATURATION VOLTAGE
vs
COLLECTOR CURRENT

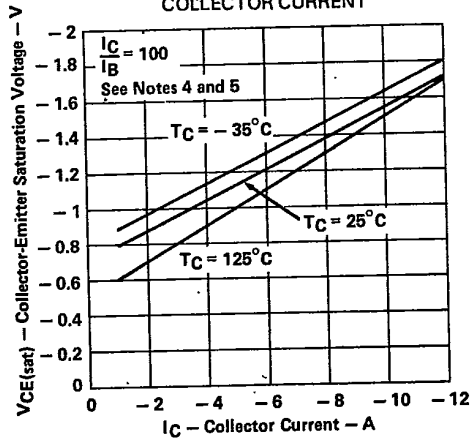


FIGURE 5

BASE-EMITTER VOLTAGE
vs
COLLECTOR CURRENT

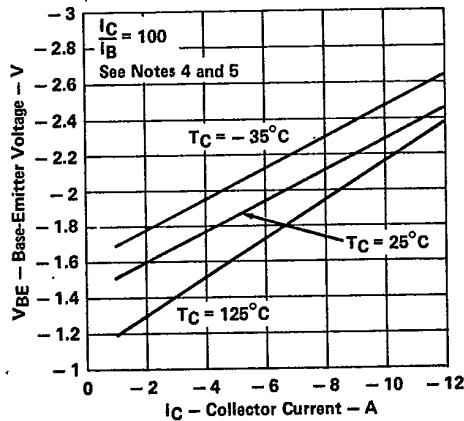


FIGURE 6

- NOTES: 4. These parameters must be measured using pulse techniques, $t_w = 300 \mu s$, duty cycle $\leq 2\%$.
5. These parameters are measured with voltage-sensing contacts separate from the current-carrying contacts and located within 3.2 mm (0.125 inch) from the device body.



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MAXIMUM SAFE OPERATING AREA

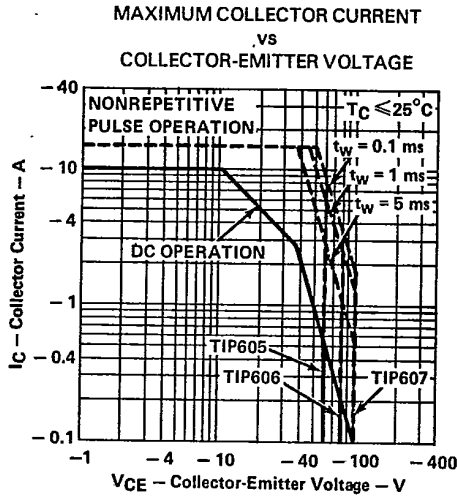


FIGURE 7

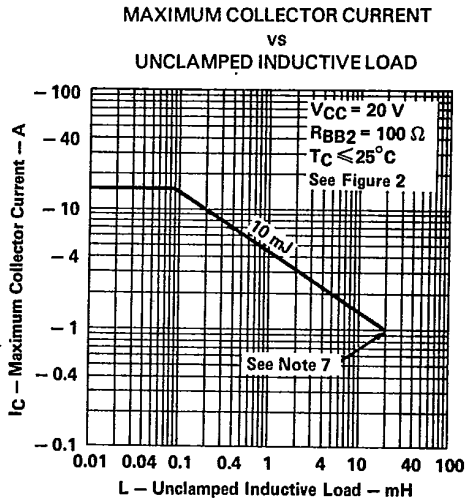


FIGURE 8

NOTE 7: Above this point the safe operating area has not been defined.

THERMAL INFORMATION

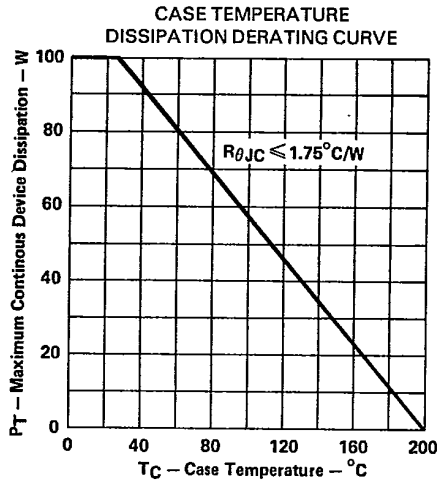


FIGURE 9

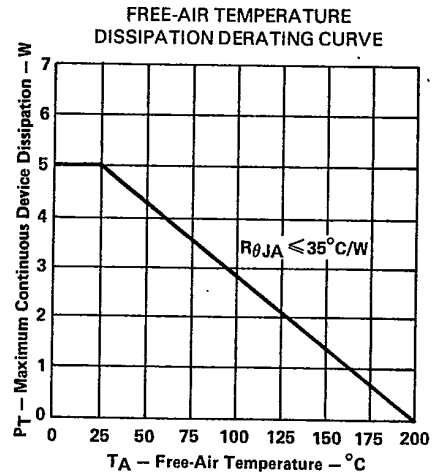


FIGURE 10

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